# **<b>&TDK** Multilayer Ceramic Chip Capacitors

#### C1608JB1E335M080AC



#### TDK item description C1608JB1E335MT\*\*\*\*

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1608 [EIA 0603]	
Status	Production	



	Size
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	3.3μF ±20%	
Rated Voltage	25VDC	
Temperature Characteristic	JB(±10%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	30ΜΩ	

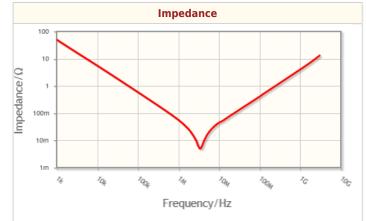
Other	
Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

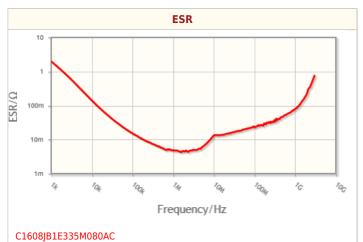
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! All specifications are subject to change without notice.

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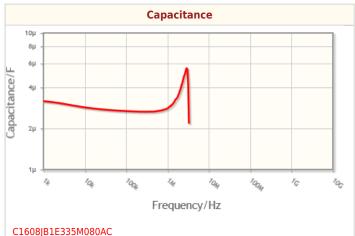


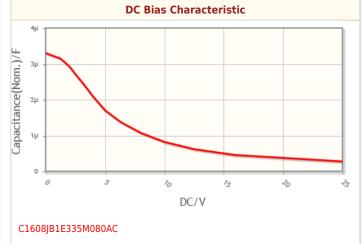




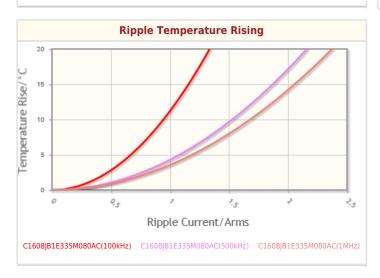
### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

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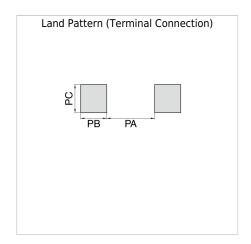
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## Associated Images



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